TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

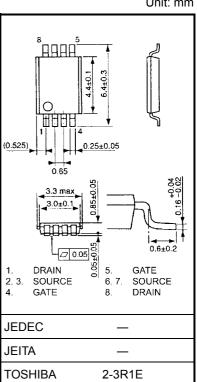
TPCS8208

Lithium Ion Battery Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: R_{DS} (ON) = 13 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 15 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 20 \ V)$ •
- Enhancement-mode: $V_{th} = 0.5 \sim 1.2 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 200 \text{ }\mu\text{A})$
- Common drain

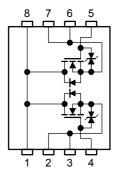
Maximum Ratings (Ta = 25°C)

Char	acteristics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	20	V	
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V _{DGR}	20	V	
Gate-source volt	age	V _{GSS}	±12	V	
Drain current	DC (Note 1)	ID	6	А	
Diamounent	Pulse (Note 1)	(Note 1) IDP 24 evice n (Note 3a) PD (1) 1.1 evice value peration (Note 3b) PD (2) 0.75	A		
Drain power dissipation (t = 10 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.1	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.75		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.6	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.35		
Single pulse avalanche energy (Note 4)		E _{AS}	46.8	mJ	
Avalanche currei	nt	I _{AR}	6	А	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.075	mJ	
Channel tempera	Channel temperature		150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 0.035 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5), please refer to the next page.

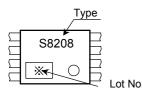
This transistor is an electrostatic sensitive device. Please handle with caution.

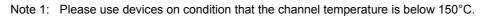
Unit: mm

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	114	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	(Note 2a) Single-device value at	R _{th (ch-a) (2)}	167		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a)} (1)	208		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	357	°C/W	

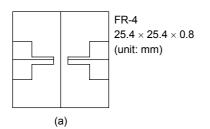
Marking (Note 6)

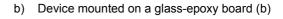


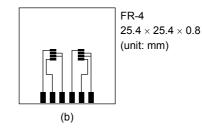


Note 2:

a) Device mounted on a glass-epoxy board (a)







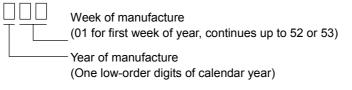
Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4: $V_{DD} = 16 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 6 A

- Note 5: Repetitive rating: pulse width limited by max channel temperature
- Note 6: \circ on lower right of the marking indicates Pin 1.

* Weekly code: (Three digits)



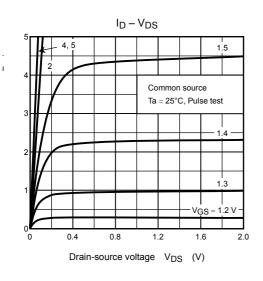
Electrical Characteristics (Ta = 25°C)

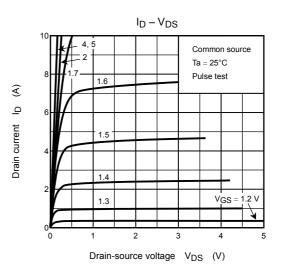
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 10~V,~V_{DS}=0~V$			±10	μA
Drain cut-OFF current		I _{DSS}	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		_	10	μA
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_	_	v
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_	_	
Gate threshold ve	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 200 \mu\text{A}$	0.5	_	1.2	V
			$V_{GS} = 2.0 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$	_	24	35	mΩ
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$		18	22	
			$V_{GS} = 4.0 \text{ V}, \text{ I}_{D} = 4.8 \text{ A}$		13	17	
Forward transfer admittance		Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 3.0 \text{ A}$	7.5	15	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		2160	_	pF
Reverse transfer	Reverse transfer capacitance				210		
Output capacitance		C _{oss}			230		
Switching time	Rise time	t _r	$V_{GS} \begin{array}{c} 5 \\ 0 \\ V \\ 0 \\ V \end{array} \right) \begin{array}{c} I_{D} = 3 \\ C \\ C \\ C \\ C \\ V \\ T \\ V \\ D \\ C \\ C$	_	5	_	- ns
	Turn-ON time	t _{on}		_	13	_	
	Fall time	t _f		_	10	_	
	Turn-OFF time	t _{off}		_	53	_	
Total gate charge (gate-source plus gate-drain)		Qg			22		
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 16 \text{ V}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}_{D} = 6 \text{ A}$		4	_	nC
Gate-drain ("miller") charge		Q _{gd}			5		

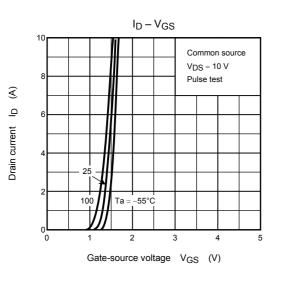
Source-Drain Ratings and Characteristics (Ta = 25°C)

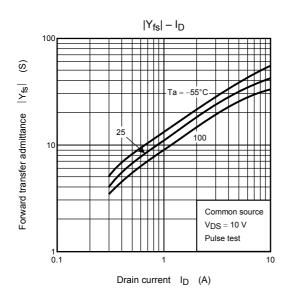
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	24	А
Forward voltage (diode)		V _{DSF}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	_		-1.2	V

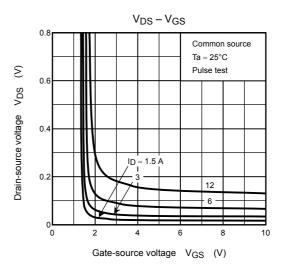
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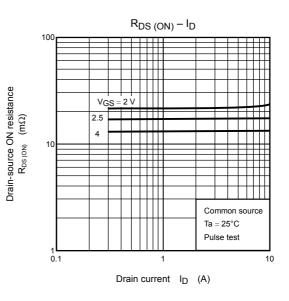




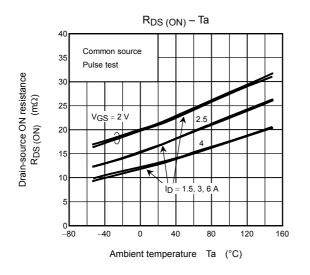


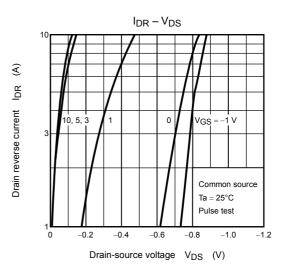


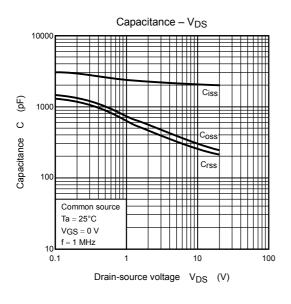


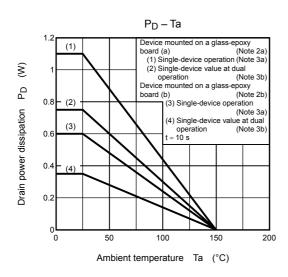


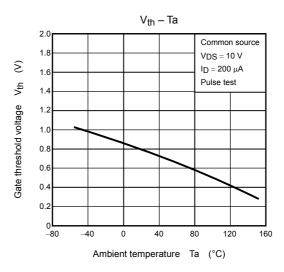
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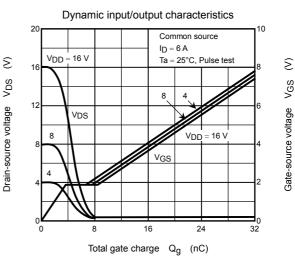








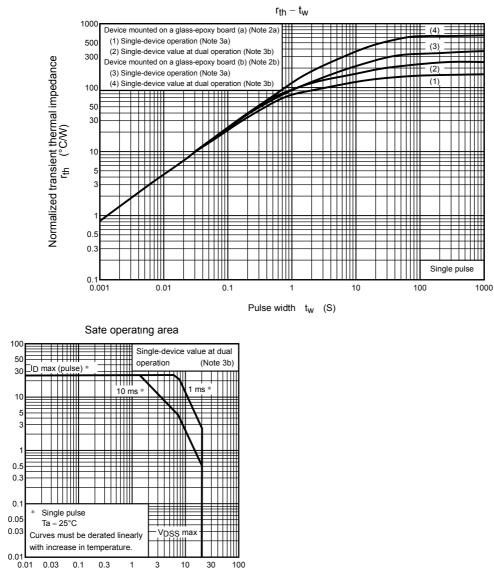




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Drain current



Drain-source voltage V_{DS} (V)

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